

文件发行章



RA0902/RA0919 SERIES GENERAL SPECIFICATION DA0007/DA0010 至 51 切 按 计

[K	AU9U2/ KAU	919 余 /	<u> </u>	治工	J 1/4		
1、GENERAL	股事项							
1.1、Sscope 适用范	围							
The specification	pplies to model RA0902/RA0919 type mainly used for consumer products Rotational type							
此规格书适用于	:规格书适用于RA0902/RA0919机型回转型							
1.2、Standard atmosph	Standard atmospheric conditions 标准状态							
Unless otherwise	Unless otherwise specified, the standard range of atmospheric conditions for making measurements and test is as follows:							
无特别规定外,	无特别规定外,测量应在以下状态下进行:							
Ambient tempera	mbient temperature 温度 :15℃ to 35℃							
Relative humidit	Relative humidity 相对湿度 :25% to 85%							
Air pressure 气月	Air pressure 气压 :86kpa to 106kpa							
If there is any do	ubt about the result	lts, measurements sh	all be made with	in the followir	ng limit:			
发生判定疑问或	另有特别要求则じ	从基准状态:			-			
Ambient tempera	ture 温度 :20+	1°C						
Relative humidit	v相对湿度 ·63%	to 67%						
Air pressure 写日		to 106kpa						
	<u>.</u>	ю тоокра						
1.3 Operating temper	ature range							
使用温度范围	-	-10℃ to 70℃						
1.4 Storage temperat	ire range							
保存温度范围		- 25℃ to 70℃						
你们 ‱没 他 四	•	200 00 100						
2、Application No	otes 使用上的	事项						
2.1、Avoid storing the	products in a plac	e at high temperatur	e, high humidity	and in corrosi	ve gases.	. Please use this product as soon		
as possible with 1	2 months limitation	on . If any remainder	left after packing	g is opened, pl	lease stor	e it with proper moistureproofing,		
gasproofing etc.	避免储藏于高温	,潮湿及腐蚀的场所	,产品购入后周	尽可能在12个	月内使用	目完。拆包装后未使用完的剩余		
产品需储藏于防	朝防毒的环境下。							
3 ELECTRICAL	CHARACT	ERISTICS电气线						
Item		Conditi	ons			Specifications		
项 目		を 他 切 枚						
3.1 Nominal total res	is The resistance b	etween terminals 1	and 3 shall be me	asured		//0 IH		
tance and telerance	迎Z1 2问阳值	·测学	and 5 shan be me	asurcu		50 K O - 20%		
	如何 1 1-3 回归且11	师丁1-5时阻值测定。 $50 \text{ K} \Omega$ ■±20%						
公称全阻抗值		11.1 1.1 .1	• . •					
3.2 Resistance law	Measurement sl	hall be made by the r	esistance law me		<u>3B</u> Taper (Refer to the attached)			
阻抗变化特性	For other proce	dures(refer JISC526		<u>3B</u> 线性(参见附贝)				
	Power rating is	Power rating is based on continuum full load operation at the						
	maximum volta	ge between terminal						
vs.ambient temperature shall be denoted on the following graph.3.3、 Power rating端子1-3间连续负载后的最大功率。								
							额定功率	额定功率 环境温度对功率影响的曲线如下图表示. 0.05W
		d p more than the second p more than the sec						
			Ambient temper	ature 周围温度(℃	2)			
文控编号: RA-001	编制时间		SUIN			CTRONIC		
版本号:08	13.07.01	SOUNDWELL	5000					
REVISION变更记事.	变 更 时 间	D&GD. T.	CHKD 宙杏	APPD 核	准 T	ITLE标题:		
6、增加止档强度选择	11 06 13	<u>按朱部</u>	<u>──技業部▼□</u>	<u> 授業部 (</u>	·	POTENTIOMETER由台哭		
7 重新敷理	12 04 02	20-11-06	20-11-06	20-11-06		OCUMENT NO 文早.		
 /、 里初 筐 生 Q	15.04.05	学曲	欧阳昌雄	、苏朝晖	ם ו	DA0009 / DA0010		
10、 生刑 笔埕	2010-9-23	1				RAU9UZ/ RAU919		

RA0902/RA0919 SERIES GENERAL SPECIFICATION RA0902/RA0919 系 列 规格 书

3 ELECTRICAL CHARACTERISTICS电气特性						
Item		Conditions			Specifications	
项目		条件条件			规格	
	Rated voltage		Maximum oj	perating voltage	50V AC	
	额定电压: E=	√/PR	最高任	吏用电压	50V AC	
	Power rating	(\mathbf{W})				
3.4 Rated voltage	P: 额定功率					
额定电压	Nominal total re	sistance				
	R: 公称全阻抗	值 (Ω)				
	When the rated v	voltage exceeds the 1	maximum operati	ing voltage.		
	the maximum op	perating voltage shal	l be the rated vol	tage		
	额定电压大于量	最高使用电压时,最高	高使用电压作为	额定电压.		
	The resistance at e	each end of the (A). Re	sistance between to	erminals 1 and 2,		
3.5 Residual resistance	terminal 2 and 3	shall be measured.	A: Angle of eff	fective rotation	R1,2: $\leq 10 \Omega$	
残留电阻	接触刷停留在(A)终端位置,在端子	-1-2间,端子2-3	间测定之电阻值.	R2,3: ≤ <u>20 Ω</u>	
		A:有效回转角度				
	Apply DC 20V b	between terminals 1-	3 to measure noi	se voltage .		
3.6、Rotational noise	(rated voltage ≤	≤20V. Apply by rate	100mVp-p Less than			
转动噪音	在端子1-3间加	直流电压20Ⅴ(额定□	电压≤20V,则以	额定电压值测试)	100mVp-p 以下	
	后,测定的杂音。	电压.	Shaft rotation	: 1 rotation /3Sec		
			轴转速:	:1回转/3秒		
	The voltage of 2	~15 V r.m.s. Shall b	e applied betwee	n terminals 1 and 3		
	and between terr	ninals 1' to 3' by me	asuring frequency	y at 1KHz. The		
	output voltage sha	ll be measured betwee	n terminals 1 and	2 and betw-		
3.7 Tracking error	een terminal 1' a	nd 2'(for the 15C and	d 25C taper. the	measurement		
连动误差	shall be made be	tween terminals 2 a				
	3') units the firs	t of these shall be the	e standard one .If	there is not any		
	doubt about the	results .d.c. voltage				
	在端子1-3间,1'-3'	间,输入频率1KHz,电	3(1) 3'(1')			
	<u> </u>	2'间的输出电压(适	用于15C和25C约	表型,端子2-3间,		
	2'-3'间也应测量	输出电压)结合第	1 KHz $2 \times 15 \text{ V}$ 2^2 2^2			
	如对测量结果没	这有质疑,则将此电	玉 值。	r.m.s		
	- · · ·					
	Input impedance of the voltmeter: $10M\Omega$ or more				1(3) 1'(3')	
	电压衣输入阻力	L:10M Ω 以上				
	[For volume contract	: (音量用)	-40~0dB	+ 4 dB or less 以下	
3.8 Insulation	Measurement sh	nall be made under th	he condition which	ch a voltage of	Between individual terminals and	
resistance	DC 250V 60s±5	5s is applied betweer	bracket 100M Ω MIN.			
绝缘阻抗	在端子和安装支	反架间施加电压 DC	端子与安装支架间电阻100MΩ以上			
3.9、Dielectric stre	A voltage of 25	OV AC shall be appl	Without arcing or breakdown.			
耐电压	terminals and bi	racket.			不得有漏电、绝缘破坏。	
	在端子和安装支	反架间施加 AC 250				
4 MECHANICAL CHARACTERISTICS机械特性						
Item		Conditi	ons		Specifications	
项目		条(4		规格	
4-1, Total mechanical	Angle of effective	ve rotation			300°+5°	
rotation全回转角度	有效旋转角度					
文控编号: RA-001	编制时间	5	SOUN	DWELL EL	ECTRONIC	
版本号:08	13.07.01	SOUNDWELL				
REVISION 变更记事:	变更时间	DSG投. 走部入	CH 拔录部查	ARR N核准	TITLE标题:	
6、 增加止档强度选项	11.06.13	20-11-06	20-11-06	20-11-06	POTENTIOMETER电位器	
 /、里初登埋 ● 舌站動田 	13.04.03	「ギ田」	欧阳昌雄	苏朝阵	DUCUMENT NU.义亏:	
0、 里胡 筐 垤	2010-9-23				KAU9UZ/ KAU919	

RA0902/RA0919 SERIES GENERAL SPECIFICATION RA0902/RA0919 系 列 抑 悠 书

AMECHANICAL		DICTICCHI						
4 MECHANICAL	<u>CHARACIE</u>	<u>KISTICS机械符</u>	"化土					
Item		Conditi	Specifications					
		余 (<u> </u>					
	Measured at star	ndard atmospheric co	$8\pm7 \text{ mNm} (80\pm70 \text{ gf.cm})$					
4.2, Rotational torque	<u>Shaft rotati</u>	on : 1 rotation						
旋转力矩	Shaft shall be able to be rotated at the temperature at -10° C							
-	在-10℃温度条	件下轴柄能转动						
4.3、Number of					without Detent			
Detemts Click					□ 1C (Center Detent中段功能)			
定位数目			□ Other其它C					
4.4 Detent Torque	Rotation speed	60°/s 旋转速度	60°/s	此项不适用	14 + 11 - mNm (140 + 110 - af - am)			
定位力矩	Measured at star	ndard atmospheric co	onditions 标准状	《态下测定	$14 \pm 11 \text{ mNm} (140 \pm 110 \text{ gl.cm})$			
4-5 Shaft stop	The following to	orsion moment load	\Box of shall be ap	plied to the	Electrical characteristics shall be			
strength	shaft for 5sec at	both ends (after fixa	ation)	-	satisfied.			
止档强度	固定后于旋转前	前后两端末加口力も	车持续5秒.		由气性能符合规定要求			
	With deter	nts 0.35 N.m(3, 5Kg	f)帯定位 0.35	5 N.m(3.5Kgf)				
	Without de	tents $0.5 \text{ N} \text{ m}(5.0\text{Kg})$	rf)不带定位0	5 Nm(5 OKgf)				
	Vitiliout de	101113 0.3 11.111(3. 0118		0 11. m (0. 01181)	Shaft without damage: Rotational			
4-6 Shaft push & pull	Push & pull stati	c load of 80 N (8K)	of) shall be anni	ied to the	torque without abnormality:			
strongth	shoft in porpon	dicular to avial direct	tions for 10 s (aft	for fivetion)	Electrical characteristics shall be			
Suengui	shart in perpend	Licular to axial unec	UOIIS IOI IU S (all	出加和UUII) 盐古兰伊持10秒	estisfied with enacification			
 田田	回足口任う相望	些且印/而田刀 印加0	UN (OKgi) HH	我何开怀劳10少。				
					湘儿 {烟 <u></u>]切, <u></u>			
4.7 Nut tightoning	Nut tighton with	$0.0 \text{ Nm} (2.01 \text{ of } \alpha)$	m)		电气性能付合规定要求			
4-7、Nut uginening	Mut uginen with	$\frac{10.0 \text{ N.m.}}{0.0 \text{ kgr.cr}}$	II)					
strengtn % 马系回蚀度	\$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$	$\frac{1}{1000}$ N. III (8.0Kg1.0	cm.)		<u> </u>			
	A momentary lo	ad of 5 N (500gr)	shall be applied	at the point 5 mm	U. /*L/20mm p-p or less 以下			
4-8 Shart Wobble	from the tip of t	ne snatt in a directio	n perpendicular t	o the axis	L is the length between mounting			
+ 11 括 功	(after fixation). 固定后左与轴』	、末端往下5mm加速	毎カロ5 N (500gf)	静裁莅	surface and measuring points			
5 ENDUDANCE C			BUHD N (DOOBL)	们时我们。	L: 回走面到测试点的距离			
<u>5 ENDURANCE C</u>								
ltem		Condifi	016		Specifications			
Item 项目		Conditi 么	ons 件		Specifications 抑 赼			
Item 项目	The terminals st	Conditi 条(all be stored at a ter	ons 件 pperature of 40°C	with relative	Specifications 规格			
Item 项目 5-1、Solder ability 但很研	The terminals shumidity of 90%	Conditi 条 个 hall be stored at a ten	ons 件 nperature of 40°C d in 168b	C with relative	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of			
近 面 项 目 5-1、 Solder ability 焊锡性	The terminals sh humidity of 90% 連時40°C 演員	Conditi 条 (nall be stored at a ten 6~95% and measured 6~95% PH 14	ons 件 nperature of 40°C d in 168h. 68小时测定	C with relative	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed			
近面 <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿力	Conditi 条 mall be stored at a ten 6~95% and measured 度90%~95% RH,16	ons 件 nperature of 40°C d in 168h. 68小时测定。	C with relative 60° C 5° C for	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面面在75% 以上想想付美			
近面 <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿质 The terminals sh 25+15 端子子20	Conditi 条 mall be stored at a ten 6~95% and measured 度90%~95%RH, 10 mall be immersed into	ons 件 nperature of 40°C d in 168h. 68小时测定。 p solder bath at 2 思博中记短2,15	C with relative	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿质 The terminals sh 3s±1s.端子在20	Conditi 条 mall be stored at a ten 6~95% and measured 度90%~95%RH, 10 mall be immersed into 50°C±5°C温度的焊積	ons 件 nperature of 40°C d in 168h. 68小时测定。 o solder bath at 2 锡槽内浸锡3±1種	C with relative 60°C±5°C for 少	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin	Conditi 条 mall be stored at a ten 6~95% and measured 度90%~95%RH, 10 nall be immersed into 50°C±5°C温度的焊 ng手工焊接	ons 件 nperature of 40°C d in 168h. 68小时测定。 o solder bath at 2 锡槽内浸锡3±1種	C with relative 60°C±5°C for 少	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿质 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature	Conditi 条 mall be stored at a ten 6~95% and measured 度90%~95% RH, 10 nall be immersed into 60°C±5°C温度的焊锁 ng手工焊接 of soldering iron:	ons 件 mperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 锡槽内浸锡3±1種 350°C less than 新	C with relative 60°C±5°C for 少 品度350°C以下	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time	Conditi 条 和all be stored at a ten 6~95% and measured 度90%~95%RH, 10 nall be immersed into 50°C±5°C温度的焊缝 ng手工焊接 of soldering iron:	ons 件 nperature of 40°C d in 168h. 68小时测定。 o solder bath at 2 易槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3	C with relative 60°C±5°C for 少 品度350°C以下 秒以内	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering槽	Conditi 条 和all be stored at a ten 6~95% and measured 度90%~95%RH, 10 nall be immersed into 50°C±5°C温度的焊锁 ng手工焊接 of soldering iron: 1 e of soldering iron:	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 锡槽内浸锡3±1種 350°C less than 彩 within 3 s.时间3	C with relative 60°C±5°C for 少 品度350°C以下 秒以内	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿质 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering權 1. Printed wiring	冬 mall be stored at a ten 6~95% and measured 度90%~95%RH, 10 mall be immersed into 50°C±5°C温度的焊付 ng手工焊接 of soldering iron: 10 e of soldering iron: 11 g board : copper class	ons 件 nperature of 40°C d in 168h. 68小时测定。 o solder bath at 2 锡槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3 d laminate board	C with relative 60°C±5°C for 少 盐度350°C以下 秒以内 with	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
Item <u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering槽 1. Printed wiring thickness of 1.6	冬 mall be stored at a ten 6~95% and measured 度90%~95% RH, 10 mall be immersed into <u>50°C±5°C温度的焊</u> of soldering iron: 10 e of soldering iron: 11 e of soldering iron: 11 g board : copper clau mm; 使用基板: t=1	ons 件 nperature of 40°C d in 168h. 68小时测定。 o solder bath at 2 锡槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3 d laminate board l.6mm的覆铜板。	C with relative 60°C±5°C for 少 品度350°C以下 秒以内 with	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
<u>项</u> 目 5-1、Solder ability 焊锡性	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering權 1. Printed wiring thickness of 1.6 2. Solder flux: F	冬 mall be stored at a ten 6~95% and measured g90%~95% RH, 10 mall be immersed into <u>50°C±5°C温度的焊</u> ng手工焊接 of soldering iron: 12 e of soldering iron: 13 e of soldering iron: 14 g board : copper claa mm; 使用基板: t=1 Flux of 0.82 specific	ons 件 nperature of 40°C d in 168h. 68小时测定。 o solder bath at 2 锡槽内浸锡3±1種 350°C less than 彩 within 3 s.时间3 d laminate board 6mm的覆铜板。 weight in bubbin	C with relative 60°C±5°C for 少 品度350°C以下 秒以内 with g type, solder flux	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
项目 5-1、Solder ability 焊锡性 5-2、Resistance to	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering權 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu	集 mall be stored at a ten 6~95% and measured g90%~95% RH, 16 mall be immersed into 60°C±5°C温度的焊 ng手工焊接 of soldering iron: 16 e of soldering iron: 16 g board : copper claa mm; 使用基板: t=1 Flux of 0.82 specific us shall be used and 10	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 湯槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3 d laminate board 1.6mm的覆铜板。 weight in bubbin bubling surface h	C with relative 60°C±5°C for 少 品度350°C以下 秒以内 with g type, solder flux leight shall be	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
項目 5-1、Solder ability 焊锡性 5-2、Resistance to soldering heat	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering權 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu defined substant	Conditi 条 和all be stored at a ten 6~95% and measured 度90%~95%RH, 10 nall be immersed into 50°C±5°C温度的焊缝 of soldering iron: 6 of soldering iron: 1 g board : copper claa mm; 使用基板: t=1 Flux of 0.82 specific as shall be used and b tially as half thickness	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 锡槽内浸锡3±1種 350°C less than 彩 within 3 s.时间3 d laminate board l.6mm的覆铜板。 weight in bubbin bubling surface h ss of substrate. Fl	C with relative 60°C±5°C for 少 品度350°C以下 秒以内 with g type, solder flux height shall be lux shall not flow	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着			
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项目 5-1、Solder ability 焊锡性 5-2、Resistance to soldering heat 焊锡耐热性 文控编号: RA-001	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering槽 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu defined substant up on substrate 助焊剂: 使用力 厚度一半的位置 3. Preheating预 Surface tempera Preheating time 4. Soldering焊持 Apply the above 编制时间	集 Anall be stored at a ten 6~95% and measured 度90%~95%RH, 10 hall be immersed into 50°C±5°C温度的焊積 of soldering iron: 10 e of soldering iron: 10 e of soldering iron: 10 e of soldering iron: 10 g board : copper claus mm; 使用基板: t=1 Flux of 0.82 specific us shall be used and be tially as half thickness surface; 定泡式比重0.82以上 量, 而且助焊剂不可 热: ture of board: 100°C : within 2 min.时间: 痿 : Solder temperat Immersion time e soldering process for	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 湯槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3 d laminate board l.6mm的覆铜板。 weight in bubbin bubling surface h ss of substrate. Fl ch焊剂,发泡面 T流入基板表面_ C or less;基板表面 C or less;基板表面 2分钟以内 ure温度: 260°C= e:within 时间: 3	C with relative 60°C±5°C for 少 盐度350°C以下 秒以内 with g type, solder flux height shall be lux shall not flow 面高大致在基板 上。 面温度100°C以下 ±5°C less 5±1 s <u>L工程适用1至2</u>	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着 Electrical characteristics shall be satisfied. No mechanical abnormality. 不得有绝缘体的破损、变形、接触无异常。			
项目 5-1、Solder ability 焊锡性 5-2、Resistance to soldering heat 焊锡耐热性 支控编号: RA-001 版本号: 08	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering槽 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu defined substant up on substrate 助焊剂:使用为 厚度一半的位置 3. Preheating预; Surface tempera Preheating time 4. Soldering焊持 Apply the above 编制时间 13.07.01	冬 Anall be stored at a ten 6~95% and measured g90%~95%RH, 10 hall be immersed into <u>50°C±5°C温度的焊</u> of soldering iron: 10 e of soldering iron: 10 e of soldering iron: 10 g board : copper claas mm; 使用基板: t=1 Flux of 0.82 specific as shall be used and b tially as half thickness surface; 定泡式比重0.82以上 置, 而且助焊剂不可 热: ture of board: 100°C : within 2 min.时间 接: Solder temperatt Immersion time e soldering process for SOUNDELL®	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 湯槽内浸锡3±1種 350°C less than 3 within 3 s.时间3 d laminate board d.6mm的覆铜板。 weight in bubbin bubling surface h ss of substrate. Fl ch焊剂,发泡雨 C or less;基板表面 C or less;基板表面 2分钟以内 ure温度:260°C= ne:within 时间: 1 or 1 or 2 times.U SOL	C with relative 60°C±5°C for 少 盐度350°C以下 秒以内 with ig type, solder flux leight shall be lux shall not flow 面高大致在基板 上。 面温度100°C以下 ±5℃ less 5±1 s L上工程适用1至2 JNDWELL	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着 Electrical characteristics shall be satisfied. No mechanical abnormality. 不得有绝缘体的破损、变形、接触无异常。 次 ELECTRONIC			
项目 5-1、Solder ability 焊锡性 5-2、Resistance to soldering heat 焊锡耐热性 支控编号: RA-001 版本号: 08 REVISION变更记事.	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering槽 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu defined substant up on substrate 助焊剂:使用力 厚度一半的位置 3. Preheating预 Surface tempera Preheating time 4. Soldering焊括 Apply the above 编制时间 13.07.01 麥爾时间	Kondition A A Condition A Condition A Condition A Condition Conditi	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 易槽内浸锡3±1種 350°C less than 彩 within 3 s.时间3 d laminate board d.6mm的覆铜板。 weight in bubbin bubling surface h ss of substrate. Fl ch焊剂,发泡面 Cor less;基板表面。 Cor less;基板表面。 Cor less;基板表面。 Cor less;基板表面。 Cor less;基板表面。 SOU SOU	C with relative 60°C±5°C for 少 温度350°C以下 秒以内 with g type, solder flux height shall be lux shall not flow 面高大致在基板 上。 面温度100°C以下 ±5℃ less 5±1 s L上工程适用1至2 JNDWELL	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着 Electrical characteristics shall be satisfied. No mechanical abnormality. 不得有绝缘体的破损、变形、接触 无异常。 K ELECTRONIC TITLE标题:			
近面目 5-1、Solder ability 焊锡性 5-2、Resistance to soldering heat 焊锡耐热性 支控编号: RA-001 版本号: 08 REVISION变更记事: 6、増加止档强度洗项	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering構 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu defined substant up on substrate 助焊剂:使用分 厚度一半的位置 3. Preheating预 Surface tempera Preheating time 4. Soldering焊括 Apply the above 编制时间 13.07.01 变更时间 11.06.13	Conditio 条 A all be stored at a ten 6~95% and measured 度90%~95% RH, 16 all be immersed into 60°C±5°C温度的焊 ng手工焊接 of soldering iron: 1 re solder temperate re soldering process fe Solder temperate re soldering proces Solder temperate re soldering proces	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 湯槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3 d laminate board l.6mm的覆铜板。 weight in bubbin bubling surface h ss of substrate. Fl ch焊剂,发泡面 了流入基板表面。 Cor less;基板表面。 Cor less;Latores.U	C with relative 60°C±5°C for 少 晶度350°C以下 秒以内 with g type, solder flux height shall be lux shall not flow 面高大致在基板 上。 面温度100°C以下 ±5°C less 5±1 s <u>L上工程适用1至2</u> JNDWELL	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着 Electrical characteristics shall be satisfied. No mechanical abnormality. 不得有绝缘体的破损、变形、接触无异常。 次 ELECTRONIC TITLE标题: POTENTIOMETER 电位器			
项目 项目 5-1、Solder ability 焊锡性 5-2、Resistance to soldering heat 焊锡耐热性 支控编号: RA-001 版本号: 08 REVISION变更记事: 6、增加止档强度选项 7、重新整理	The terminals sh humidity of 90% 温度40°C,湿力 The terminals sh 3s±1s.端子在26 Manual solderin Bit temperature Application time Dip soldering槽 1. Printed wiring thickness of 1.6 2. Solder flux: F coating apparatu defined substant up on substrate 助焊剂: 使用力 厚度一半的位置 3. Preheating预 Surface tempera Preheating time 4. Soldering焊持 Apply the above 编制时间 13.07.01 变更时间 11.06.13 13.04.03	Condition A Condition A Condition	ons 件 nperature of 40°C d in 168h. 68小时测定。 5 solder bath at 2 湯槽内浸锡3±1種 350°C less than ¾ within 3 s.时间3 d laminate board 1.6mm的覆铜板。 weight in bubbin bubling surface h ss of substrate. Fl chmpl 剂, 发泡雨 1流入基板表面 2分钟以内 ure温度: 260°C e:within 时间: 3 or 1 or 2 times.U SOL C/LEX 部在 20-11-06 FB/TU B 44	C with relative 60°C±5°C for 少 盐度350°C以下 秒以内 with og type, solder flux leight shall be lux shall not flow 面高大致在基板 上。 面温度100°C以下 ±5°C less 5±1 s L工程适用1至2 JNDWELL	Specifications 规格 A new uniform coating of solder shall cover a minimum of 75% of the surface being immersed. 浸渍面须有75%以上焊锡付着 Electrical characteristics shall be satisfied. No mechanical abnormality. 不得有绝缘体的破损、变形、接触 无异常。 K ELECTRONIC TITLE标题: POTENTIOMETER电位器 DOCUMENT NO 文号:			

RA0902/RA0919 SERIES GENERAL SPECIFICATION RA0902/RA0919 系 列 规格 书

5 ENDURANCE CHARACTERISTICS耐久性能							
Item		Conditio	Specifications				
项 目		条 作	规_格				
5-3、Resistance to heat 耐热性	The potentiomete in a thermostati after maintainin surface moistur 后 罢王當泪當	r shall be stored at a ten ic chamber. Then the ng at standard atmosp e removed. 温度70° 混1小时除去水海后	Change in total resistance is relative to the value before test : ±20% 总阻变化值:初期值的±20%				
5-4、Resistance to Cold 耐寒性 5-5、 Damp heat 耐湿性	The potentiome 96h±4h in a the taken out of the And measure th atmospheric co 放置后,置于行 The potentiome relative humidi Then the potent moisture shall b be subjected to 温度40°C±2°C	<u>他1</u> 小时候会小商店 eter shall be stored at a ermostatic chamber.T chamber and its surfa- e potentiometer whic onditions for 1h.温度 <u>常温常湿1小时除去</u> eter shall be stored at a ity of 90% to 95% for iometer shall be taken be removed. And mea standard atmospheric ,湿度90%-95%,恒温	Change in total resistance is relative to the value before test: ±20% 总阻变化值:初期值的±20% Change in total resistance is relative to the value before test: +35-5% 总阻变化值:初期值的+35-5% Insulation resistance: 20MΩ or more 绝缘阻抗: 20MΩ 以上 Rotational Noise:150mV p-p less than				
5-6、 Change of temperature 温度循环试验	小时后, 置于常 The potentiome temperature cyc shall be remove subjected tostan 以下条件温度试 后,1小时内测试 1 2 stand 3 stand 4	法温常湿1小时除去水 ter shall be subjected eles, each as shown in ed. And measure the p ndard atmospheric con 连续5个周期的试验) 定。 Temperature 温度 -10°C±3°C dard atmospheric con 常温 70°C±2°C dard atmospheric con 常温	转动噪音: 150mV p-p 以下 Change in total resistance is relative to the value before test : ±30% 总阻变化值: 初期值的±30% Insulation resistance:100MΩ or more 绝缘阻抗: 100MΩ以上 Dielectric strength : Without damage to parts arcing or breakdown etc. 耐电压:无损伤,变形,绝缘破坏等 情形. Appearance: There shall be no dafo- rmation or cracks of molded part. 外观: 塑胶部分无形成破裂				
5-7、 Endurance 耐久性	The moving cor end stop to the o 90% of effective And the moving total 10 000±20 轴以600周/小时 效旋转角度超过	ntact without electrica other and returned to e angle). This proced g contact shall be subj 00 cycles.(5 000 to 8 (寸(来回算1周)的速度 过90%, 共10 000±20	Change in total resistance is relative to the value before test: ±15% 总阻变化值:初期值的±15% Rotational noise:150mVp-p or less 转动噪音: 150mV p-p 以下 Rotational torque:Initial torque 50%. 转动力矩:不低于初期规格值的50% Residual resistance 残留电阻: R1,2:< 20 Ω; R2,3:< 40 Ω				
文控编号: RA-001 版本号: 08 REVISION变更记事: 6、增加止档强度选项 7、重新整理	编制时间 13.07.01 变更时间 11.06.13 13.04.03	SOUNDWELL® DSGD.主办 技术部 20-11-06 空古	SO CHKD, 审查 技术部 20-11-06 欧阳星雄	UNDWELL APPD.核准 技术部 20-11-06 末朝晖	ELECTRONIC TITLE标题: POTENTIOMETER电位器 DOCUMENT NO.文号:		
8、重新整理	2016-9-25	<u>+</u> щ	141月1日14	RA0902/RA0919			

RA0902/RA0919 SERIES GENERAL SPECIFICATION

RA0902/RA0919 系 列 规格书

	<u> </u>	<u> 40902/RA09</u>	<u>19 系 夕</u>	<u> </u>	书 5/5		
Rotational switch p	ortion 旋转开	关部分					
Note: The following s	specification is	only suitable for R	A0902/RA091	potentiometer se	eries with switch construction.		
注: 以下规格只适用	月于此RA0902/H	RA0919电位器系列	」带开关结构。				
1-1、Rated capacity	(Resistance lo	bad): DC 16V 3	А				
额定容量(电阻负	〕荷): DC 16	V 3 A					
1-2、Electrical char	acteristics电 ²	气性能					
ITEM	CONDITIONS				SPECIFICATIONS		
项 目		条 件			规 格		
1-2-1、SW Contact					50 mΩ MAX		
resistance			50 mΩ以下				
接触阻抗							
1-2-2、Insulation res-	Measurement sh	all be made under th	Between individual terminals and bracke				
istance	250V DC 60 s±	5 s is applied betwee	50 MΩ Min.				
绝缘电阻	在端子与安装支	支架间施加电压DC	在端子与安装支架间50 MΩ以上				
1-2-3 Dielectric	A voltage of 250	0V AC 60s±5s be ap	Without arcing or breakdown.				
strength	and bracket.		不得有漏电、绝缘损坏。				
耐电压	在端子与安装支	支架间施加AC250V	$60s\pm5s$.				
1-3 Mechanical cha	racteristics机	械性能					
ITEM		CONDITIO	SPECIFICATIONS				
项目	条 件				规格		
1-3-1, Switch type					Single pole and single throw		
开关型式					(rotational on)		
					单极单投(旋转ON)		
1-3-2, Switch rotation							
angle开关回转角度					50° Max.		
1-3-3, Switch action	Rotation speed 60°/ S						
开关作动力	旋转速度 60°/S		10N.m (1Kgf.cm) Max.				
1-4 Endurance chai	racteristics耐	久性能					
ITEM		CONDITIC	DNS		SPECIFICATIONS		
项目	条件				规格		
Rotational operating life	The potentiomer	ter's shall be rotated	SW Contact resistance : 1Ω max.				
开关旋转寿命	600 cycles/h wit	thout electrical load.	Operating force:Initial force 50%.				
	在无负荷条件	下,对轴以每小时60	接触电阻:1Ω以下.				
			开关动作力为初期值的50%。				
主持位日 - 54 - 661	,	4					
乂控编号: KA-001	编制时间	5	SOU	NDWELL E	LECTRONIC		
版 本 号: 08	13.07.01	SOUNDWELL					
REVISION变更记事:	变更时间	DSGD.主办	CHKD. 审查	APPD.核准	TITLE标题:		
6、增加止档强度选项	11.06.13 技术部 技术部 技术部				POTENTIOMETER电位器		
7、重新整理	13.04.03	20-11-06		20-11-06	DOCUMENT NO.文号:		
8、重新整理	2016-9-25	, H	VEA PH EI 2#	7777HT	RA0902/RA0919		

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